



# packaging materials

## Global Semiconductor Packaging Materials Outlook

*Global Semiconductor Packaging Materials Outlook* is a comprehensive market research study that examines semiconductor packaging technology trends and their impact on the packaging materials markets. The report quantifies the packaging materials markets by segment and by region, highlights new opportunities for emerging package form factors, defines supplier market share, and presents market forecasts through 2021.

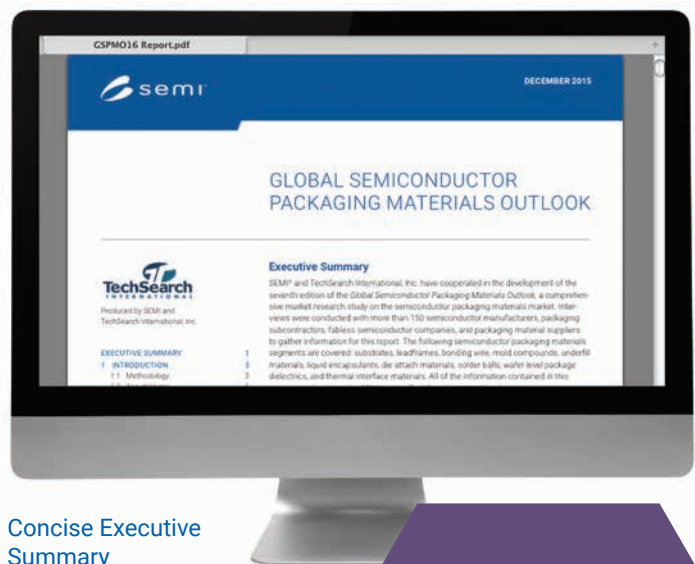
*Global Semiconductor Packaging Materials Outlook* is an essential business tool for anyone interested in the plastic packaging materials arena. Packaging materials directly affect the performance, reliability and cost of semiconductors, and advancements in packaging materials technology offer the potential for significant improvement across all these areas.

### FEATURES

- Technology trends
- Regional market size
- Five-year market forecasts
- Supplier market share
- Market size in revenue and units
- Capacity and utilization trends
- Supply chain Issues

### METHODOLOGY

The source of information for this study are in-person interviews with over 150 material suppliers, packaging subcontractors, and semiconductor manufacturers from around the world. The authors of this report used primary research and modeling to develop market size information, and developed five-year market forecasts based on different scenarios of new technology penetration and market growth.



- Concise Executive Summary
- Adobe Acrobat chapters for each materials segment
- Excel workbook file summarizing market information
- PowerPoint charts, ideal for presentations

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### SEMI CONTACT:

**Dan P. Tracy, Ph.D**  
Senior Director of Industry Research  
and Statistics, SEMI  
Tel: 1.408.943.7987  
[dtracy@semi.org](mailto:dtracy@semi.org)



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### TECHSEARCH INTERNATIONAL CONTACT:

**Ms. E. Jan Vardaman**  
President and Founder,  
TechSearch International, Inc.  
Tel: 1.512.372.8887  
[jan@techsearchinc.com](mailto:jan@techsearchinc.com)